

**IN THE CLAIMS:**

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The status of each claim is indicated with one of (original) or (cancelled).

Please CANCEL claims 5-8 in accordance with the following:

1. (ORIGINAL) A semiconductor device having an additional functional element comprising:

a semiconductor element, at least on one face of which first and second electrodes are arranged;

a wiring board having first and second connection pads on a face of which the semiconductor element is mounted;

connection means for electrically connecting the first electrode with the first connection pad so that a small gap can be formed between the one face of the semiconductor element and the mounting face of the wiring board when the one face of the semiconductor element is arranged being directed toward the mounting face of the wiring board; and

an element having a specific additional function arranged in the gap formed between a region of the second electrode of the semiconductor element and a region of the second connection pad of the wiring board, wherein

the additional functional element is connected with the second electrode on the one face thereof and also connected with the second connection pad on the other face thereof so that a specific electric function can be exhibited.

2. (ORIGINAL) A semiconductor device according to claim 1, wherein the connection means is a solder bump, one face of the additional functional element is connected with the second electrode by means of ultrasonic connection, anisotropic conductive adhesive film or anisotropic conductive adhesive paste, and the other face of the additional functional element is connected with the connection pad by means of soldering.

3. (ORIGINAL) A semiconductor device according to claim 1, wherein a plurality of electrodes for signal use, which are used as the first electrodes, are arranged in an outer peripheral region on one face of the semiconductor element, electrodes for electric power supply

and for grounding, which are used as third and fourth electrodes, are arranged in a central region other than the second electrode, the additional functional element is arranged in the gap defined between the central region of the semiconductor element and the wiring board, and the third and the fourth electrodes are electrically connected with third and fourth connection pads on the wiring board through a plurality of conductive vias penetrating from one face of the additional functional element to the other face thereof.

4. (ORIGINAL) A semiconductor device according to claim 1, wherein the additional functional element is an extremely thin type passive element or active element, or alternatively the additional functional element is an extremely thin type capacitor, resistor or inductance.

5. (CANCELLED)

6. (CANCELLED)

7. (CANCELLED)

8. (CANCELLED)